

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

1. (currently amended) An anisotropic-electroconductive adhesive comprising:
an insulating adhesive component containing a radical polymerizable compound and a polymerization initiator; and
a plurality of insulating coated electroconductive particles dispersed in the insulating adhesive component, the insulating coated electroconductive particle having a coating layer made of insulating thermoplastic resin on a surface of an electroconductive particle,
wherein an exothermic peak temperature of the insulating adhesive component is in the range of 80°C~120°C and a softening point of the insulating thermoplastic resin is lower than ~~an~~ the exothermic peak temperature of the insulating adhesive component.
2. (cancelled)
3. (original) An anisotropic-electroconductive adhesive according to claim 1,
wherein the coating layer made of the insulating thermoplastic resin has a thickness of 0.01 μ m~10 μ m.
4. (original) An anisotropic-electroconductive adhesive according to claim 1 or 3,
wherein the electroconductive particle is made by forming a metal thin layer onto a surface of a nucleus material.
5. (currently amended) An anisotropic-electroconductive adhesive according to claim 4 ~~1 or 2~~,
wherein the insulating adhesive component further includes thermosetting resin and a curing agent.
6. (original) An anisotropic-electroconductive adhesive according to claim 1,
wherein the radical polymerizable compound is acrylate based or metacrylate based compound.
7. (currently amended) An anisotropic-electroconductive adhesive according to

claim 1 ~~or~~ 2,

wherein the polymerization initiator is organic peroxide.

8. (currently amended) An anisotropic-electroconductive adhesive according to claim 1 ~~or~~ 2,

wherein the insulating adhesive component further includes thermoplastic resin.

9. (cancelled)

10. (original) A circuit connection structure in which the anisotropic-electroconductive adhesive defined in the claim 1 is interposed between circuit boards respectively having circuit electrodes faced each other so that the circuit electrodes are electrically connected each other.